CTM3051, CTM3052, CTM3053

600V Random Phase 4-Pin Mini-Flat Phototriac Optocoupler

Features

- High isolation 3750 VRMS
- Peak Breakdown Voltage 600V
- Temperature range - 55 ℃ to 100 ℃
- Regulatory Approvals
  - UL - UL1577 (E364000)
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC – GB4943.1, GB8898
  - IEC60065, IEC60950
- Green Package

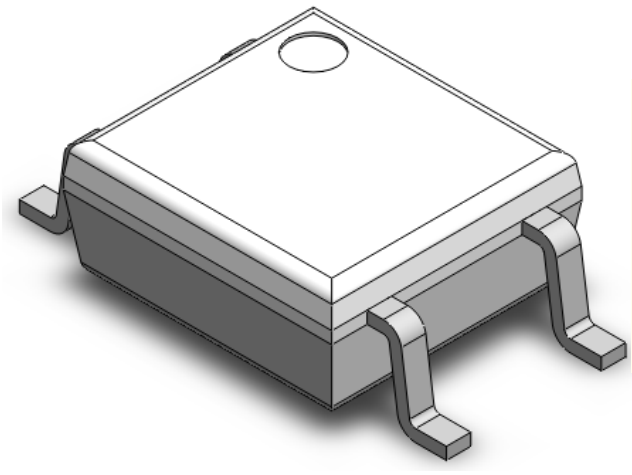
Description

The CTM3051, CTM3052, CTM3053 series consists of a Random Phase Photo Triac optically coupled to a gallium arsenide Infrared-emitting diode in a 4-lead Mini Flat package.

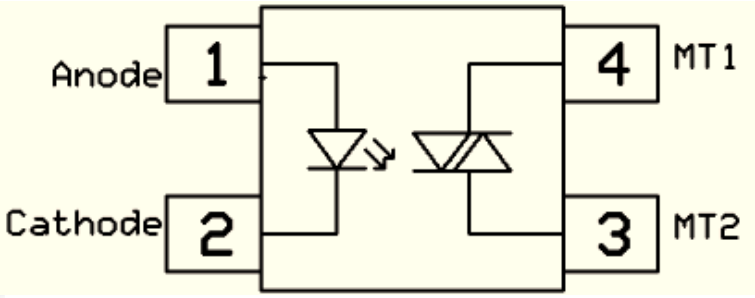
Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch

Package Outline



Schematic



Absolute Maximum Rating at 25°C

Symbol	*Parameters*	*Ratings*	*Units*	*Notes*
V_{ISO}	Isolation voltage	3750	V_{RMS}	
T_{OPR}	Operating temperature	-55 ~ +100	°C	
T_{STG}	Storage temperature	-55 ~ +125	°C	
T_{SOL}	Soldering temperature	260	°C	
P_{TOT}	Total power dissipation	200	mW	
Emitter				
I_F	Forward current	60	mA	
$I_{F(TRANS)}$	Peak transient current (≤1μs P.W,300pps)	1	A	
V_R	Reverse voltage	6	V	
P_D	Power dissipation	100	mW	
Detector				
P_D	Power dissipation	300	mW	
V_{DRM}	Off-State Output Terminal Voltage	600	V	
I_{TSM}	Peak Repetitive Surge Current	1	A	

Electrical Characteristics T_A = 25℃ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	I_F=10mA	-	-	1.5	V	
I_R	Reverse Current	V_R = 6V	-	-	5	μA	
C_{IN}	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
I_{DRM}	Peak Blocking Current		I_F= 0mA, V_{DRM}= Rated V_{DRM}	-	-	100	nA	
V_{TM}	Peak On-State Voltage		I_F= Rated I_{FT}, I_{TM}= 100mA	-	-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	CTM305X	V_{PEAK} = 600V	1000	-	-	V/μs	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
I_{FT}	Input Trigger Current	CTM3051	Terminal Voltage = 3V	-	-	15	mA	
		CTM3052		-	-	10		
		CTM3053		-	-	5		
I_H	Holding Current			-	250	-	μA	
R_{IO}	Isolation Resistance		V_{IO}= 500V_{DC}	$1x10^{11}$	-	-	Ω	
C_{IO}	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

Typical Characteristic Curve

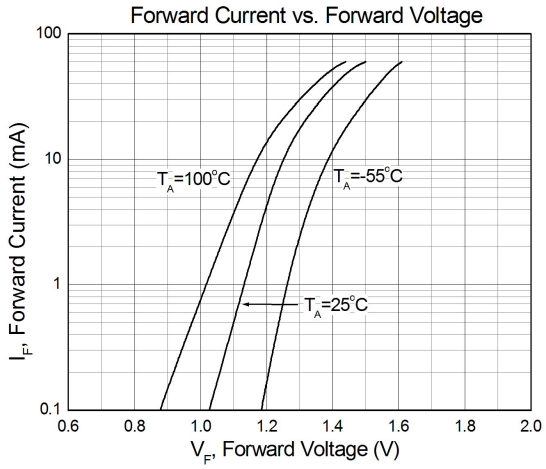


Figure 1

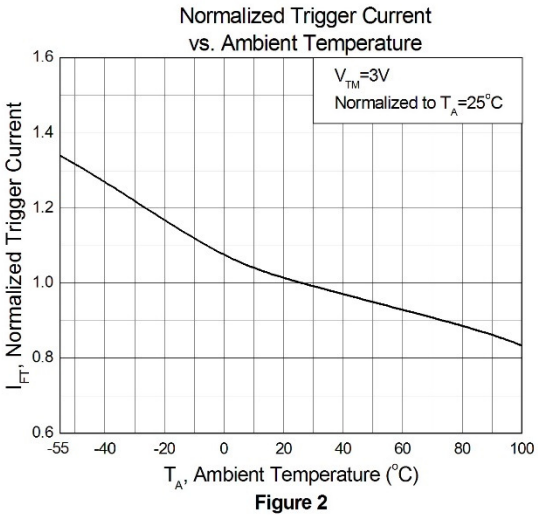


Figure 2

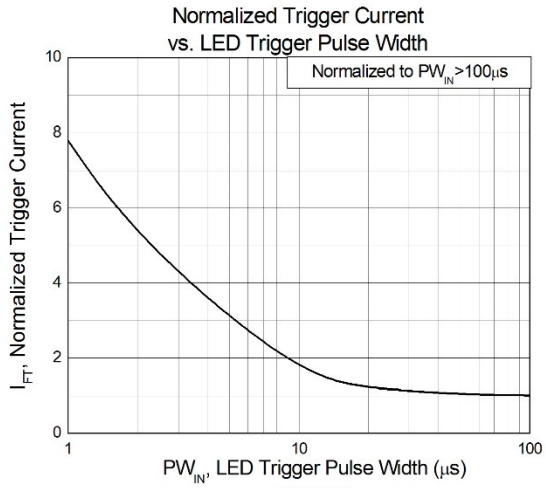


Figure 3

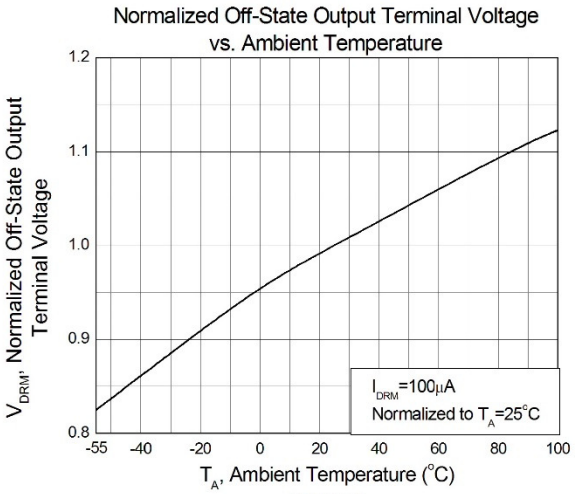


Figure 4

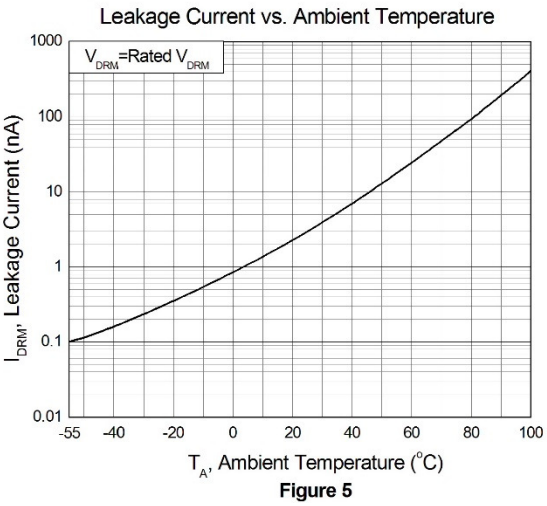


Figure 5

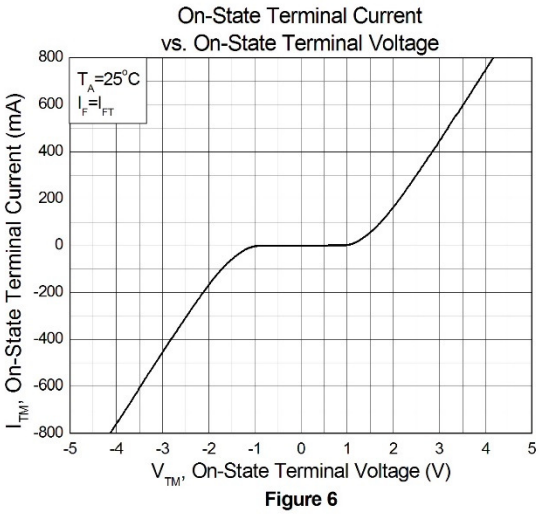


Figure 6

Typical Characteristic Curve

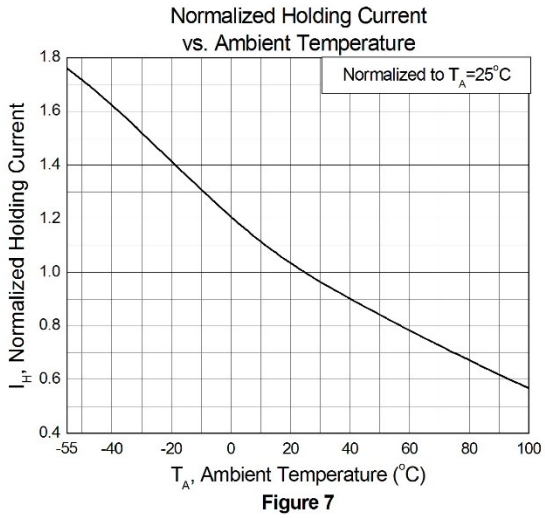
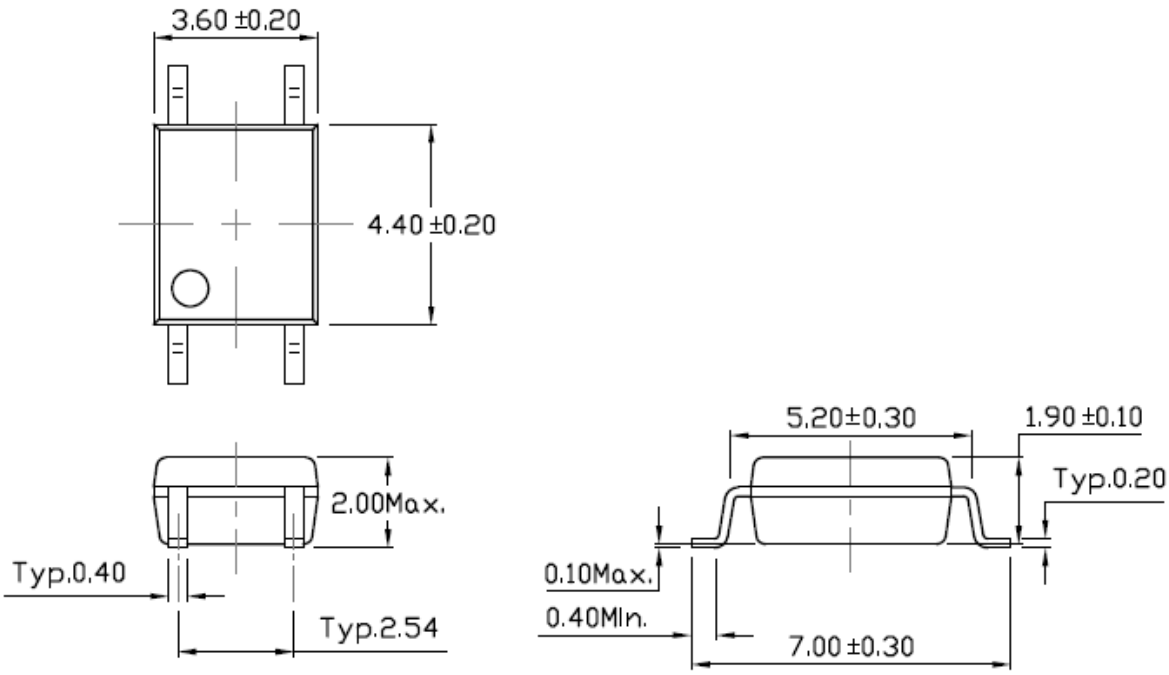
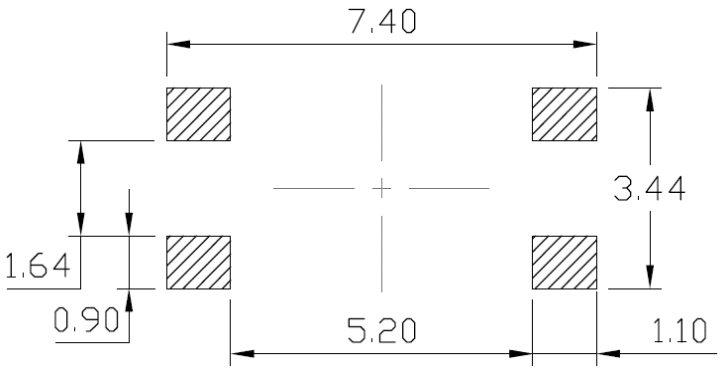


Figure 7

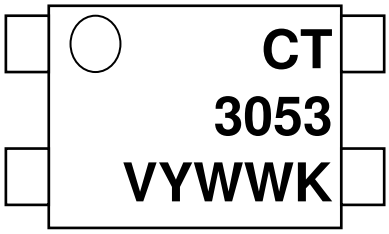
Package Dimension *Dimensions in mm unless otherwise stated*



Recommended Solder Mask *Dimensions in mm unless otherwise stated*



Marking Information



Note:

CT : Denotes “CT Micro”
3053 : Product Number
V : VDE Option
Y : Fiscal Year
WW : Work Week
K : Manufacturing Code

Ordering Information

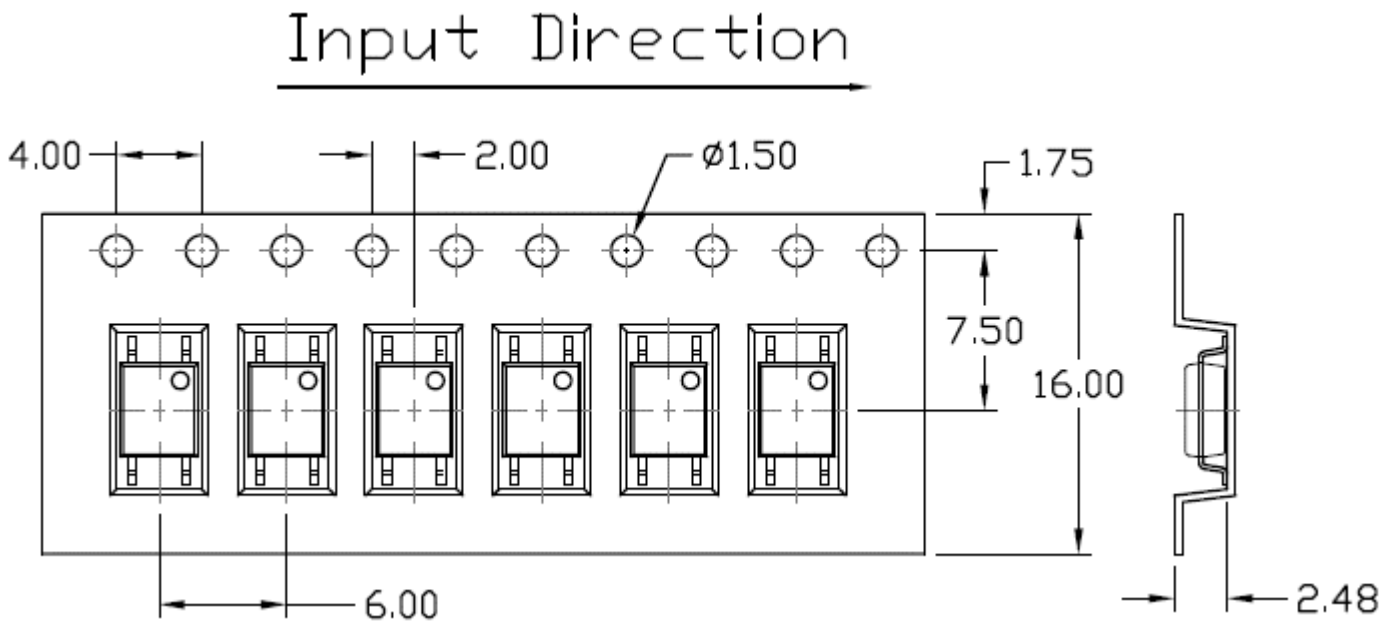
CTM30XX(V)(Z)

XX = Part No. (XX=51, 52 or 53)
V = VDE Option (V or None)
Z = Tape and reel option (T1 or T2)

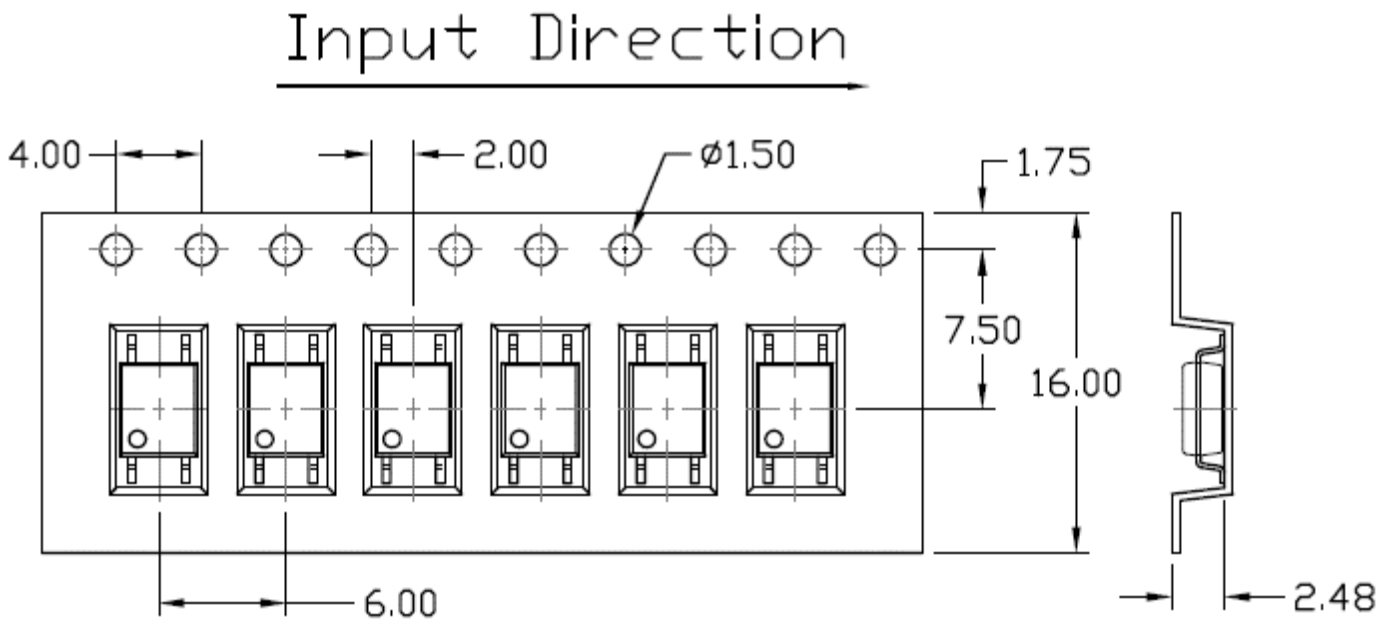
Option	*Description*	*Quantity*
T1	Surface Mount Lead Forming – With Option 1 Taping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000 Units/Reel

Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

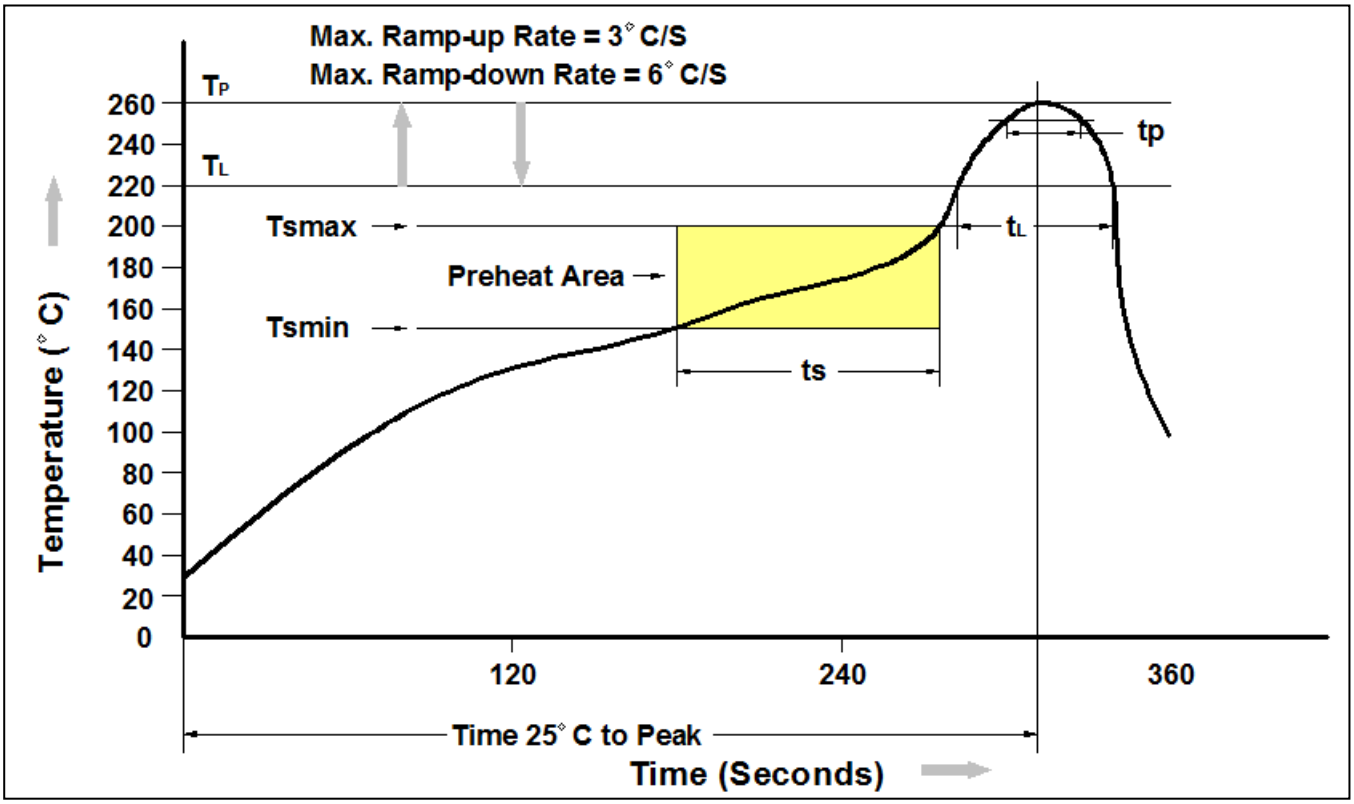
Option T1



Option T2



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150℃
Temperature Max. (Tsmax)	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3℃/second max.
Liquidous Temperature (T_L)	217℃
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260℃ +0℃ / -5℃
Time (t_P) within 5℃ of 260℃	30 seconds
Ramp-down Rate (T_P to T_L)	6℃/second max
Time 25℃ to Peak Temperature	8 minutes max.

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